

IN THE CLAIMS

Please amend the claims as follows:

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Claim 1 (Canceled).

Claim 2 (Previously Presented): The electronic component packaging container according to Claim 8, wherein the multilayer polyester sheet has a total light transmittance of at least 85% and a cloudiness of at most 10%.

Claim 3 (Previously Presented): The electronic component packaging container according to Claim 8 which has an antistatic treatment applied to one or both sides.

Claim 4 (Previously Presented): A sheet which comprises a base layer containing a polyethylene terephthalate type resin and a polycarbonate type resin, a surface layer containing a polycarbonate type resin formed on at least one side of the base layer, and a coating layer of an electrically conductive coating formed on at least one side of the surface layer, wherein the base layer contains from 70 to 95 wt% of the polyethylene terephthalate type resin and from 5 to 30 wt% of the polycarbonate type resin based on the total amount of the polyethylene terephthalate type resin and the polycarbonate type resin, the thickness of the surface layer is from 10 to 30% of the total thickness, and the coating layer has a surface specific resistance within a range of from 10^4 to $10^{14} \Omega$.

Claim 5 (Original): The sheet according to Claim 4, wherein the electrically conductive coating contains carbon black and/or an antistatic agent.

Claim 6 (Original): The sheet according to Claim 5, wherein the antistatic agent is a high polymer antistatic agent.

Claim 7 (Currently Amended): An electronic component packaging container which comprises the sheet as defined in Claim 4 which has been embossed.

Claim 8 (Currently Amended): An electronic component packaging container, comprising a base layer containing a polyethylene terephthalate type resin and a polycarbonate type resin and a surface layer containing a polycarbonate type resin, formed on at least one side of the base layer, wherein the base layer contains from 70 to 95 wt% of the polyethylene terephthalate type resin and from 5 to 30 wt% of the polycarbonate type resin based on the total amount of the polyethylene terephthalate type resin and the polycarbonate type resin, and the thickness of the surface layer is from 10 to 30% of the total thickness, which is [[a]] an embossed carrier tape.

Claim 9 (Original): A packaged product of an electronic component, wherein the electronic component is stored in the carrier tape as defined in Claim 8 and heat-sealed with a cover tape.

Claim 10 (Currently Amended): The electronic component packaging container according to Claim 7, which is [[a]] an embossed carrier tape.

Claim 11 (Currently Amended): A packaged product of an electronic component, wherein the electronic component is stored in the embossed carrier tape as defined in Claim 10 and heat-sealed with a cover tape.

Claim 12 (Currently Amended): An electronic component packaging container
comprising a sheet according to Claim 4, wherein the coating layer has a thickness of from
0.5 to 10 μm .